

FEATURES

Ideal for printed circuit board
 Reliable low cost construction utilizing
 molded plastic technique
 High temperature soldering guaranteed:
 260°C/10 seconds at 5 lbs., (2.3kg) tension
 Small size, simple installation
 High surge current capability
 Glass passivated chip junction
 Green compound(halogen&Sb₂O₃ free)

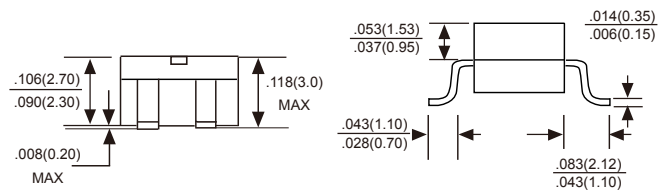
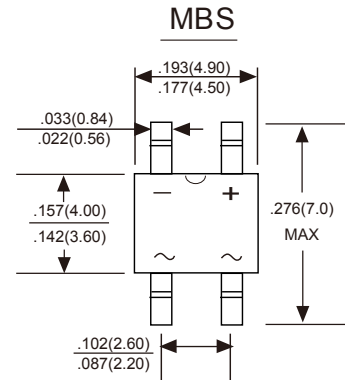
MECHANICAL DATA

Case: Molded plastic body

Terminals: Plated leads solderable per MIL-STD-750,
Method 2026

Polarity: Polarity symbols marked on case

Mounting Position: Any



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load derate current by 20%.

	SYMBOLS	MB2S	MB4S	MB6S	MB8S	MB10S	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum average forward rectified current On glass-epoxy P.C.B. On aluminum substrate	$I_{F(AV)}$	0.5 0.8					A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	30					A
Maximum instantaneous forward voltage drop per leg at 0.4A	V_F	1.0					V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=100^\circ\text{C}$	I_R	5 100					μA μA
Typical thermal resistance	$R_{\theta JL}$ $R_{\theta JA}$	28 85					$^\circ\text{C/W}$
Operating temperature range	T_J	-55 to +150					$^\circ\text{C}$
storage temperature range	T_{STG}	-55 to +150					$^\circ\text{C}$



FIG.1 FORWARD DERATING CURVE

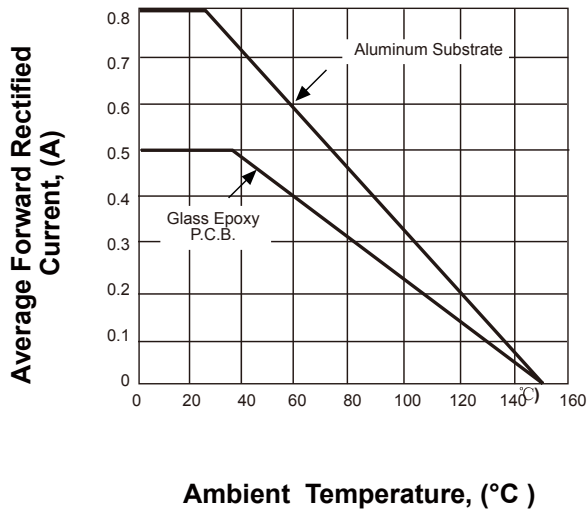


FIG.2 PEAK FORWARD SURGE CURRENT

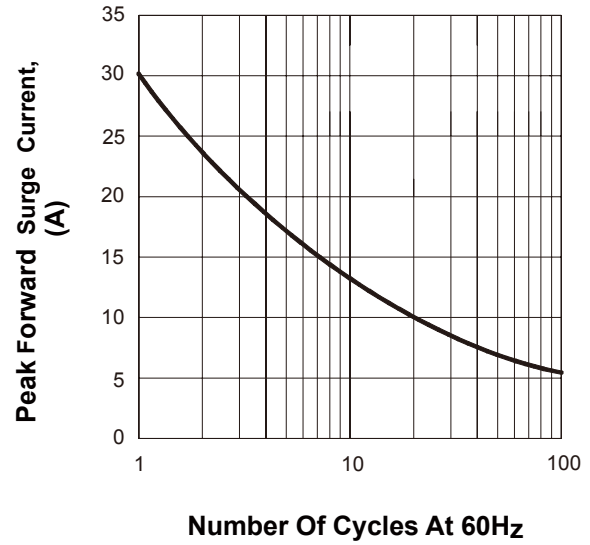


FIG.3 TYPICAL FORWARD CHARACTERISTICS

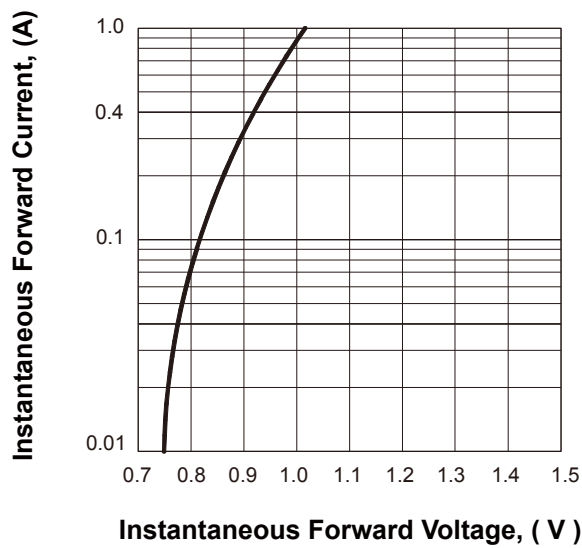


FIG.4 TYPICAL REVERSE CHARACTERISTICS

